

Layer	Stack up	Supplier	Supplier Description	Description	Type	Tg	εr	Base Thickness	Processed Thickness
1		Electra Polymers		Liquid PhotolImageable Mask	SolderMask			4.000	
		Circuitfoil		Copper Foil	Copper			0.018	0.038
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.063
		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.168
2		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.035	0.035
3		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.135
4		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.035	0.035
5		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.135
6		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.200	0.200
7		Shanghai Nanya	NY2150	PrePreg 7628	Dielectric	150.000	4.200	0.187	0.168
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.063
8		Circuitfoil		Copper Foil	Copper			0.018	0.038
		Electra Polymers		Liquid PhotolImageable Mask	SolderMask			4.000	

1.62

Copper Thickness = 0.286 | Dielectric Thickness = 1.331 | Solder Mask Thickness = 0.050 | Stack Up Thickness = 1.617 | Stack Up Thickness with Soldermask = 1.667 | Stack Up Cost = 51.00 |

Drill Image	1st Layer	2nd Layer	Column Position
	1	8	1

Notes

StackName: Mlb8_Standard1.6mm_TraX	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1
Date: 2017/05/04	Associated Documents:					
Author: H.Ndala						
Department: Tech						
Site: Diep River						